



## Dual N-Channel PowerTrench MOSFET

#### **General Description**

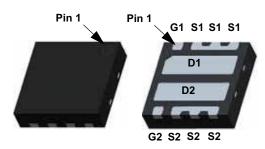
This device includes two 40V N-Channel MOSFETs in a dual **DFN3X3** (3 mm X 3 mm MLP) package. The package is enhanced for exceptional thermal performance.

#### Features

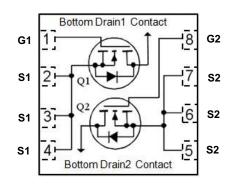
- Max  $r_{DS(on)}$  = 20 m $\Omega$  at V<sub>GS</sub> = 10 V, I<sub>D</sub> = 7 A
- Max  $r_{DS(on)}$  = 27 m $\Omega$  at  $V_{GS}$  = 4.5 V,  $I_D$  = 6 A
- Low Inductance Packaging Shortens Rise/Fall Times
- Lower Switching Losses
- 100% Rg Tested
- Termination is Lead-free and RoHS Compliant

#### Applications

- Battery Protection
- Load Switching
- Point of Load







#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
7N40	RMD7N40DN	DFN3X3	13 "	12 mm	3000 units

#### Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

Symbol	Parame	eter		Ratings	Units
V <sub>DS</sub>	Drain to Source Voltage			40	V
V <sub>GS</sub>	Gate to Source Voltage			±20	V
I <sub>D</sub>	Drain Current -Continuous	T <sub>C</sub> = 25 °C		20	
	-Continuous	T <sub>A</sub> = 25 °C	(Note 1a)	7	Α
	-Pulsed		(Note 4)	50	
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	13	mJ
D	Power Dissipation	T <sub>C</sub> = 25 °C		12	w
PD	Power Dissipation $T_A = 25 \text{ °C}$ (Note 1a)			1.9	V
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Tempera		-55 to +150	°C	

#### **Thermal Characteristics**

R <sub>0JC</sub>	Thermal Resistance, Junction to Case	9.7	°C/M
$R_{ ext{ heta}JA}$	Thermal Resistance, Junction to Ambient (Note 1a	) 65	°C/W

### Electrical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units

#### **Off Characteristics**

BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	I <sub>D</sub> = 250 μA, V <sub>GS</sub> = 0 V	40			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		23		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 32 V, V <sub>GS</sub> = 0 V			1	μA
I <sub>GSS</sub>	Gate to Source Leakage Current, Forward	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V			100	nA

#### **On Characteristics**

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \ \mu A$	1.0	1.8	3.0	V
$\Delta V_{GS(th)} \Delta T_J$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = 250 µA, referenced to 25 °C		-5		mV/°C
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 7 A		16	20	
<b>r</b>	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 6 \text{ A}$		21	27	mΩ
r <sub>DS(on)</sub> Static Drain to Source On Resistant		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 7 A T <sub>J</sub> = 125 °C		23	29	- 11152
9 <sub>FS</sub>	Forward Transconductance	V <sub>DD</sub> = 5 V, I <sub>D</sub> = 7 A		27		S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	<u> </u>		513	720	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V f = 1MHz		137	195	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 = 110112		9.3	15	pF
Rg	Gate Resistance		0.1	2.6	3.6	Ω

#### **Switching Characteristics**

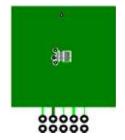
t <sub>d(on)</sub>	Turn-On Delay Time		5.5	11	ns
t <sub>r</sub>	Rise Time	$V_{DD}$ = 20 V, I <sub>D</sub> = 7 A V <sub>GS</sub> = 10 V, R <sub>GEN</sub> = 6 Ω	1.2	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> = 10 V, R <sub>GEN</sub> = 6 Ω	13	24	ns
t <sub>f</sub>	Fall Time		1.3	10	ns
~	Total Gate Charge	V <sub>GS</sub> = 0 V to 10 V	7.6	11	nC
Q <sub>g(TOT)</sub>	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V} \text{ V}_{DD} = 20 \text{ V}$	3.6	5.1	nC
Q <sub>gs</sub>	Gate to Source Charge	I <sub>D</sub> = 7 A	1.5		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		1.0		nC

#### **Drain-Source Diode Characteristics**

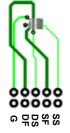
V <sub>SD</sub>	Source to Drain Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 7 A (Note 2)	0.85	1.3	V
		$V_{GS} = 0 V, I_S = 1.4 A$ (Note 2)	0.75	1.2	v
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 7 A, di/dt = 100 A/μs	16	29	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$r_F = 7 A$ , divat = 100 A/µs	3.9	10	nC

NOTES:

1. R<sub>0JA</sub> is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0JC</sub> is guaranteed by design while R<sub>0CA</sub> is determined by the user's board design.



a. 65 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



b. 155 °C/W when mounted on a minimum pad of 2 oz copper

2. Pulse Test: Pulse Width <  $300 \ \mu$ s, Duty cycle < 2.0 %. 3. E<sub>AS</sub> of 13 mJ is based on starting T<sub>J</sub> = 25 °C, L = 3 mH, I<sub>AS</sub> = 3 A, V<sub>DD</sub> = 40 V, V<sub>GS</sub> = 10 V. 100% tested at L = 0.1 mH, I<sub>AS</sub> = 11 A. 4. Pulse Id refers to Figure.11 Forward Bias Safe Operation Area.

## RATING AND CHARACTERISTICS CURVES (RMD7N40DN)

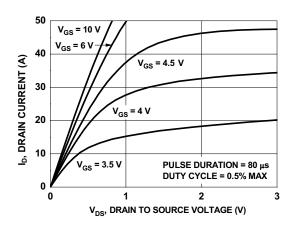
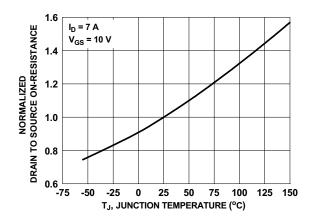
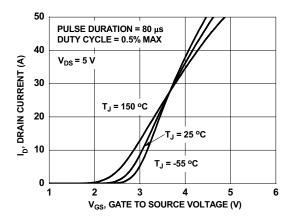


Figure 1. On-Region Characteristics









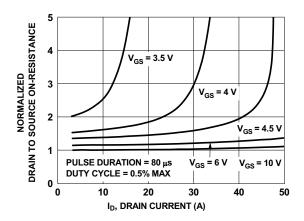


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

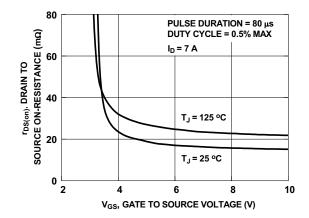


Figure 4. On-Resistance vs Gate to Source Voltage

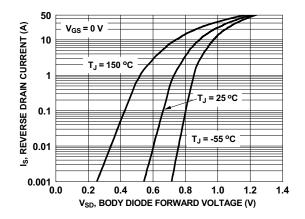
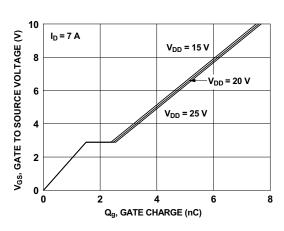


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

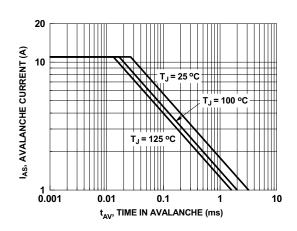




# RATING AND CHARACTERISTICS CURVES (RMD7N40DN)

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Figure 7. Gate Charge Characteristics





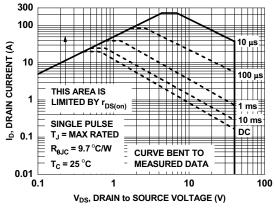


Figure 11. Forward Bias Safe Operating Area

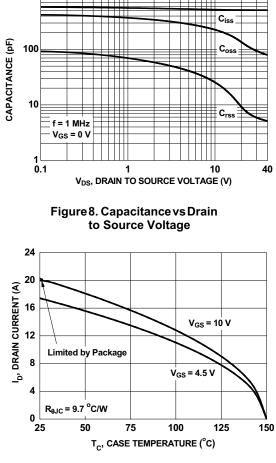


Figure 10. Maximum Continuous Drain Current vs Case Temperature

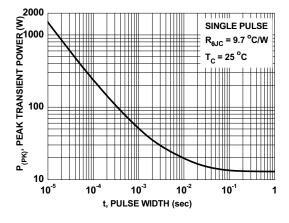
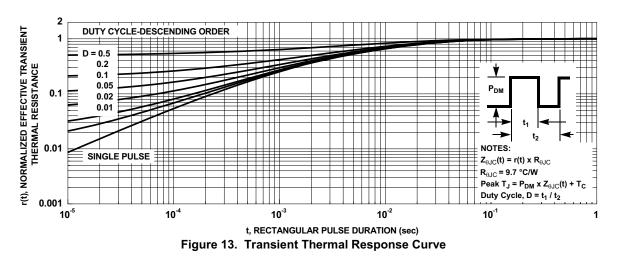


Figure 12. Single Pulse Maximum Power Dissipation

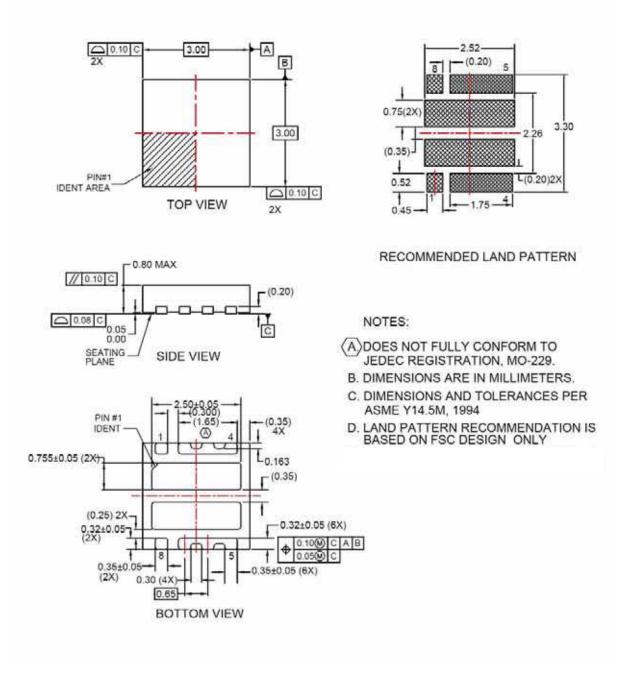




**RATING AND CHARACTERISTICS CURVES (RMD7N40DN)** 



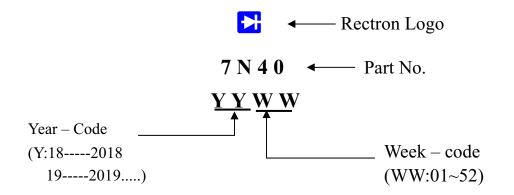
### **Dimensional Outline and Pad Layout**







# Marking on the body





Package	Tube (pcs/tube)	Tube (pcs/inner box)	Tube (pcs/cartoon)	Tape&Reel (pcs/reel)	Tape&Reel (pcs/inner box)	Tape&Reel (pcs/cartoon)
DFN	100	10,000	100,000	2,500	5,000	40,000
SOP-8	100	10,000	100,000	4,000	4,000	20,000
TSSOP-8	100	32,000	128,000	3,000	6,000	48,000
SOT-23-3L				3,000	30,000	120,000
SOT-23-6L				3,000	30,000	120,000
SOT-23(6R)				3,000	30,000	120,000
SOT-363				3,000	30,000	120,000
SOT-523				3,000	30,000	120,000
SOT223				2,500	2,500	20,000
TO-220	50	1,000	5,000			
TO-220F	50	1,000	10,000			
TO-247	30	300	1,200			
TO-251	80	4,000	40,000			
TO-251S(4R)	80	4,000	40,000			
TO-252-2L(4R)	80	4,000	40,000	2,500	2,500	25,000
TO-263-2L	50	1,000	10,000	800	800	8,000
TO-3P	30	300	3,000			
TO-92				1,000(袋装)	10,000	100,000



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